Method for molecular bonding of silicon and glass substrates

ABSTRACT OF THE DISCLOSURE

The present invention concerns a method for bonding a first substrate (1a) having a first surface (2a) to a second substrate (1b) having a second surface (2b), characterized in that it comprises the steps of:

- holding the first substrate (1a) by at least two support points (S1, S2),
- positioning the first substrate (1a) and the second substrate (1b) so that the first surface (2a) and the second surface (2b) face each other,
- deforming the first substrate (1a) by applying between at least one pressure point (P1) and the two support points (S1, S2), a strain (F) toward the second substrate (1b),
- bringing the deformed first surface (2a) and the second surface (2b) into contact,
- progressively releasing the strain (F).

Figure 6b